

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :
Joo Ho LEE *et al.* : Confirmation No. 2626
U.S. Patent Application No. 10/790,723 : Group Art Unit: 2826
Filed: March 3, 2004 : Examiner: Fetsum Abraham
For: WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING
METHOD THEREOF

AMENDMENT

COMMISSIONER FOR PATENTS
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Sir:

The following amendments and remarks are submitted in response to the Official Action
dated *March 27, 2006*.